

NCE N&P-Channel complementary Power MOSFET

Description

The NCE60NP1515K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

N channel

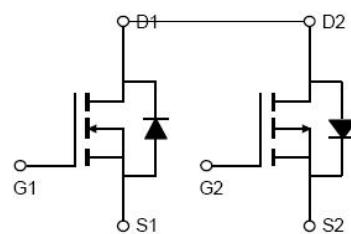
- $V_{DS} = 60V, I_D = 15A$
- $R_{DS(ON)} < 40m\Omega @ V_{GS} = 10V$
- $R_{DS(ON)} < 71m\Omega @ V_{GS} = 4.5V$

p channel

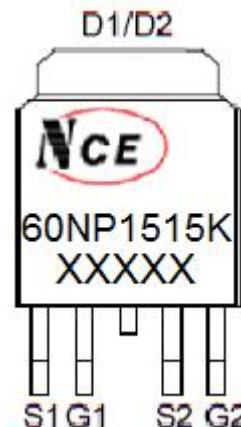
- $V_{DS} = -60V, I_D = -15A$
- $R_{DS(ON)} < 65m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} < 85m\Omega @ V_{GS} = -4.5V$
- High density cell design for ultra low $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- H-bridge
- Inverters



Schematic diagram



Marking and pin assignment

100% UIS TESTED!

100% ΔV_{ds} TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
60NP1515K	NCE60NP1515K	TO-252-4L	-	-	-

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V_{DS}	60	-60	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current $T_c=25^\circ C$	I_D	15	-15	A
		10.6	-10.6	
Pulsed Drain Current (Note 1)	I_{DM}	60	-60	A
Maximum Power Dissipation	P_D	35		W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175		°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	$R_{\theta JC}$	4.3	°C/W
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N-Channel Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=60\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	1.2	1.9	2.5	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=10\text{A}$	-	34	40	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=10\text{A}$		59	71	
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=10\text{A}$	8	-	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=30\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1.0\text{MHz}$	-	551	-	PF
Output Capacitance	C_{oss}		-	42	-	PF
Reverse Transfer Capacitance	C_{rss}		-	38.5	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{DD}}=30\text{V}, \text{R}_{\text{L}}=3\Omega$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_{\text{G}}=3\Omega$	-	5	-	nS
Turn-on Rise Time	t_r		-	2.6	-	nS
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$		-	16.1	-	nS
Turn-Off Fall Time	t_f		-	2.3	-	nS
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=30\text{V}, \text{I}_D=10\text{A}, \text{V}_{\text{GS}}=10\text{V}$	-	17.1	-	nC
Gate-Source Charge	Q_{gs}		-	3.6	-	nC
Gate-Drain Charge	Q_{gd}		-	4.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=10\text{A}$	-		1.2	V
Diode Forward Current (Note 2)	I_s		-	-	15	A
Reverse Recovery Time	t_{rr}	$\text{TJ} = 25^\circ\text{C}, \text{IF} = 10\text{A}$ $\text{di/dt} = 100\text{A}/\mu\text{s}$ (Note 3)	-	29	-	nS
Reverse Recovery Charge	Q_{rr}		-	49	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $\text{Tj}=25^\circ\text{C}, \text{VDD}=30\text{V}, \text{VG}=10\text{V}, \text{L}=0.5\text{mH}, \text{Rg}=25\Omega$

N-Channel Typical Electrical and Thermal Characteristics (Curves)

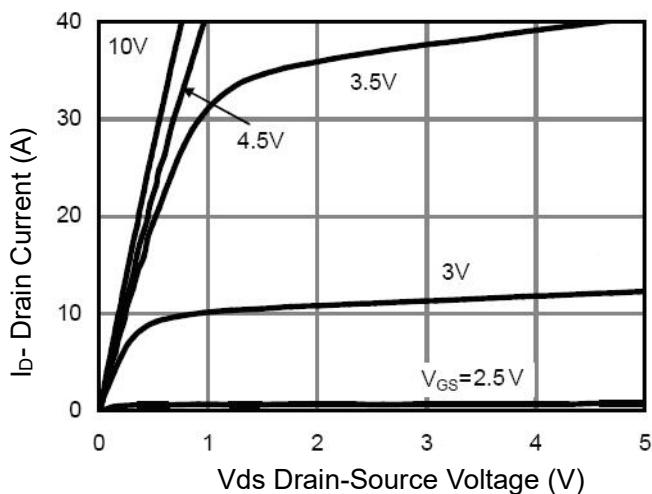


Figure 1 Output Characteristics

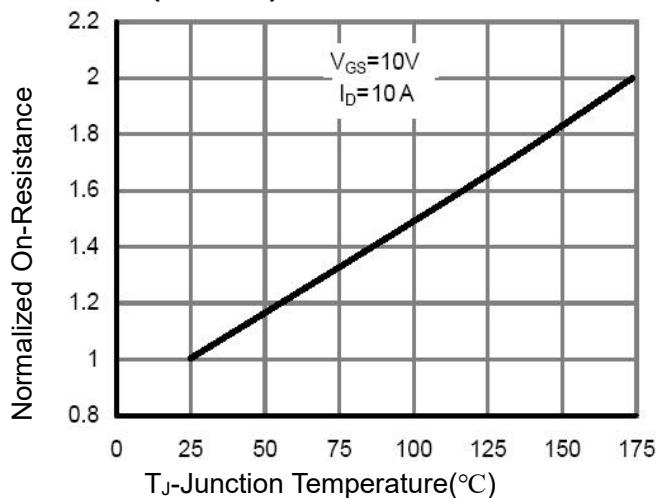


Figure 4 Rdson-Junction Temperature

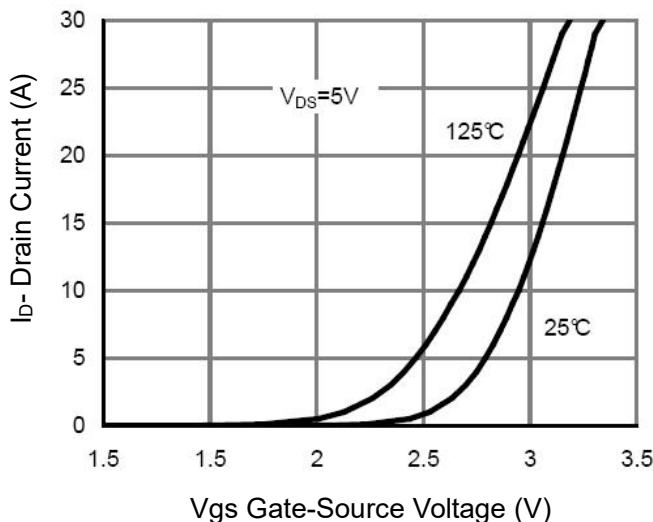


Figure 2 Transfer Characteristics

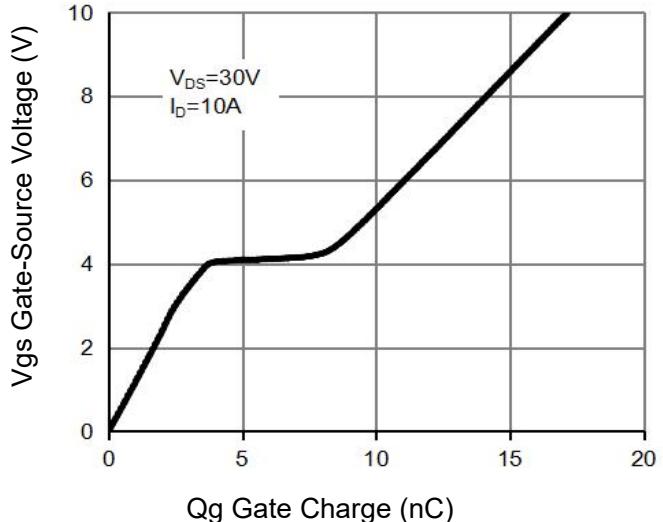


Figure 5 Gate Charge

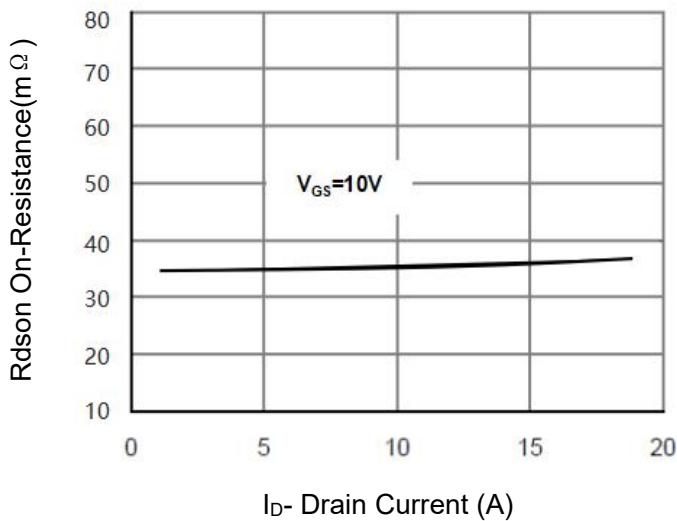


Figure 3 Rdson- Drain Current

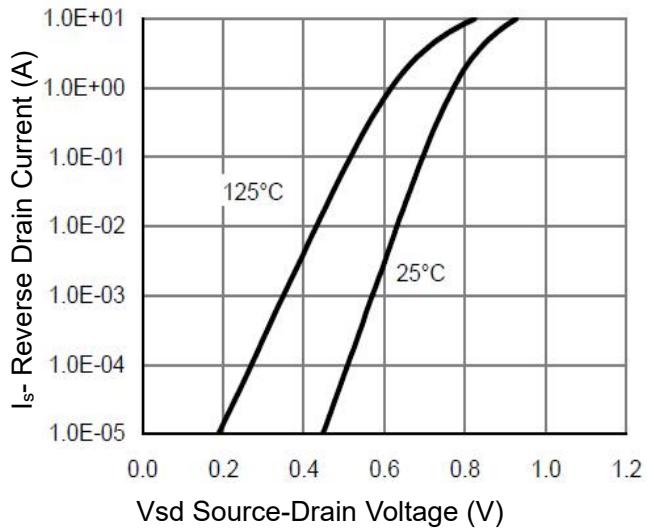
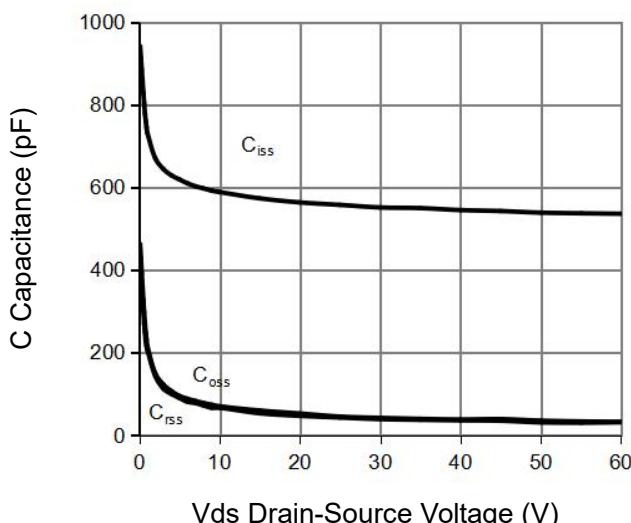
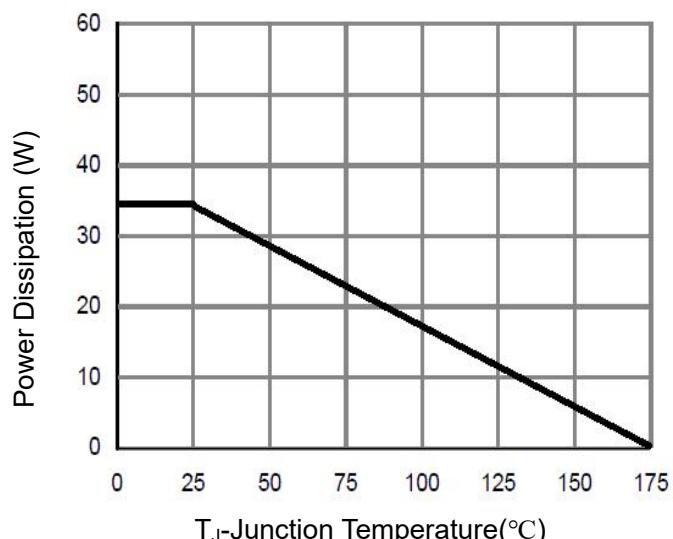
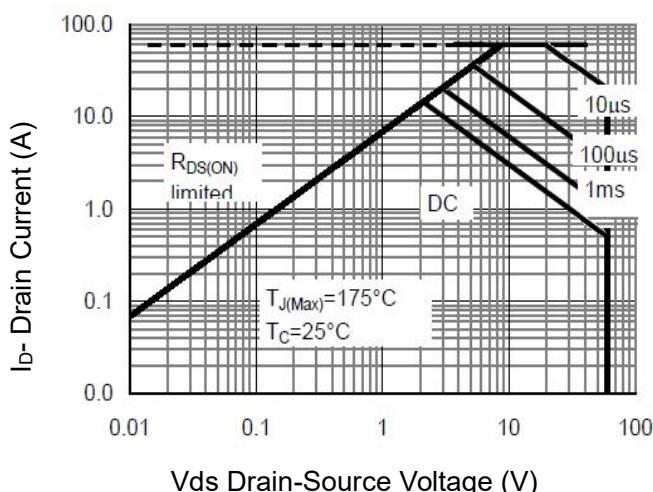
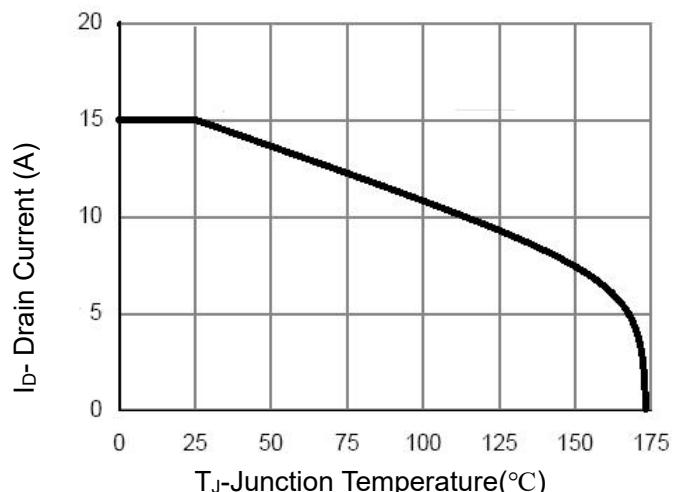
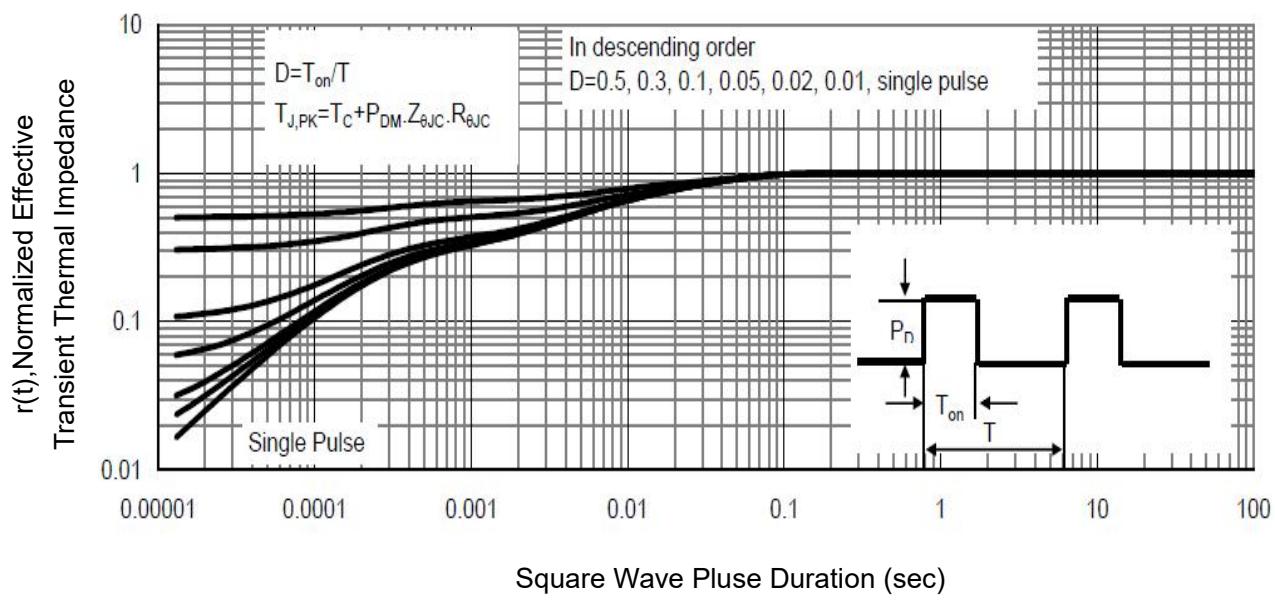


Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area

Figure 10 ID Current De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance

P-Channel Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=-250\mu\text{A}$	-60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=-60\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=-250\mu\text{A}$	-1.0	1.5	-2.0	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=-10\text{V}, \text{I}_D=-10\text{A}$	-	55	65	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_D=-10\text{A}$	-	65	85	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=-5\text{V}, \text{I}_D=-10\text{A}$	-	15	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=-30\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $F=1.0\text{MHz}$	-	1108	-	PF
Output Capacitance	C_{oss}		-	73.7	-	PF
Reverse Transfer Capacitance	C_{rss}		-	58.2	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=-30\text{V}, \text{R}_L=3\Omega,$ $\text{V}_{\text{GS}}=-10\text{V}, \text{R}_G=3\Omega$	-	8	-	nS
Turn-on Rise Time	t_r		-	4	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	32	-	nS
Turn-Off Fall Time	t_f		-	7	-	nS
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=-30, \text{I}_D=-10\text{A},$ $\text{V}_{\text{GS}}=-10\text{V}$	-	23.4	-	nC
Gate-Source Charge	Q_{gs}		-	4.1	-	nC
Gate-Drain Charge	Q_{gd}		-	4.8	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=-10\text{A}$	-		-1.2	V
Diode Forward Current (Note 2)	I_S		-	-	-15	A
Reverse Recovery Time	t_{rr}	$\text{T}_J = 25^\circ\text{C}, \text{I}_F = -10\text{A}$ $d\text{i}/dt = -100\text{A}/\mu\text{s}$ (Note 3)	-	25		nS
Reverse Recovery Charge	Q_{rr}		-	31		nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

P-Channel Typical Electrical and Thermal Characteristics (Curves)

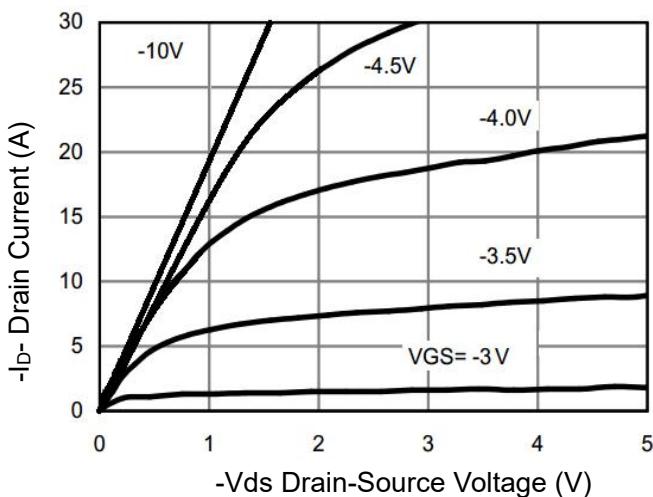


Figure 1 Output Characteristics

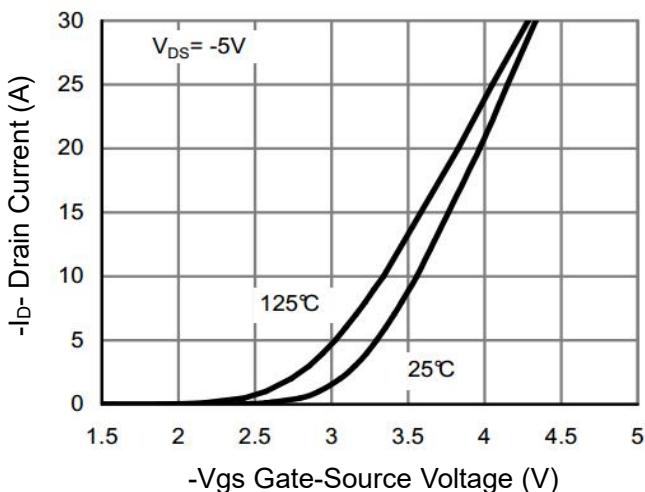


Figure 2 Transfer Characteristics

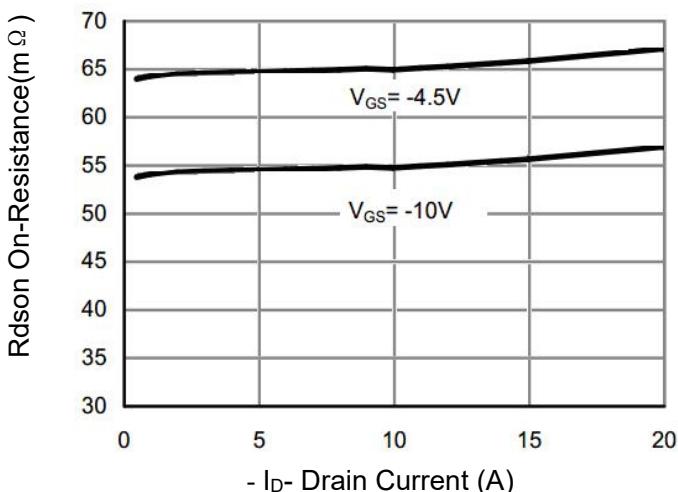


Figure 3 Rdson- Drain Current

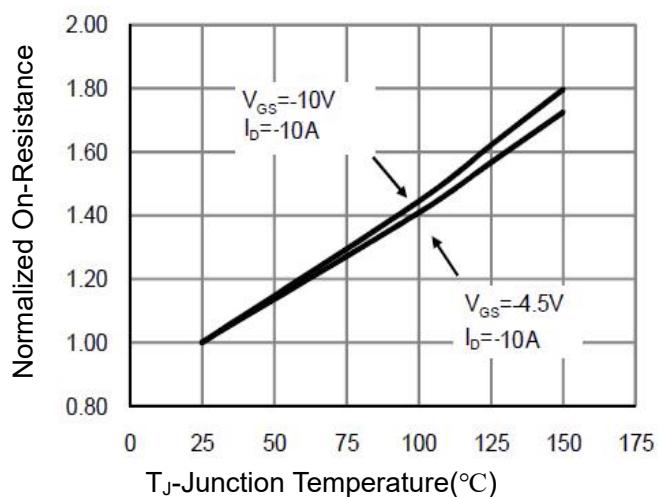


Figure 4 Rdson-Junction Temperature

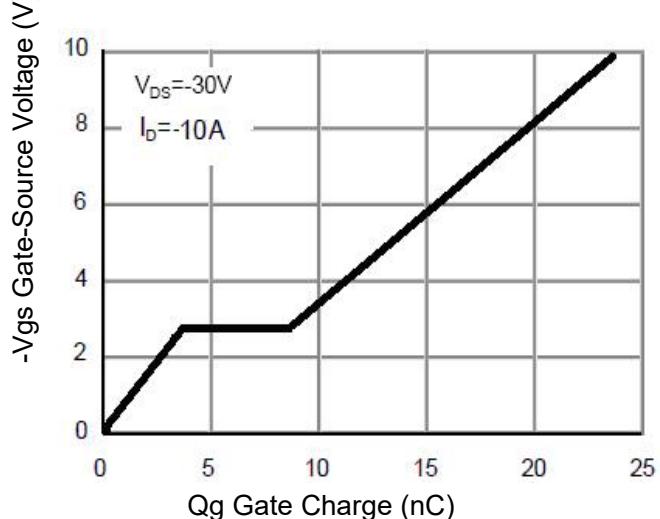


Figure 5 Gate Charge

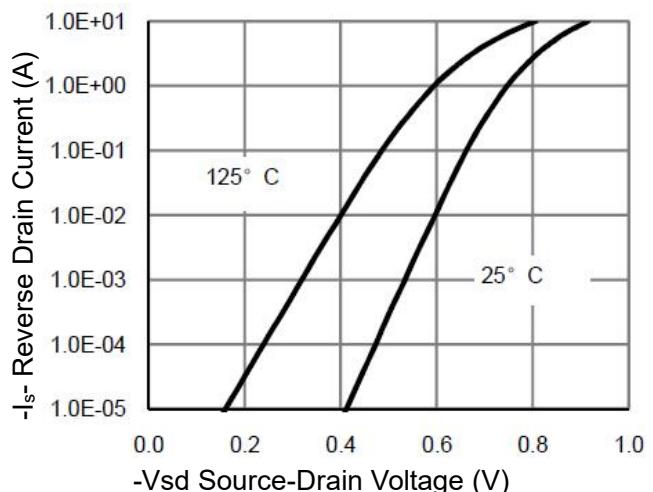


Figure 6 Source- Drain Diode Forward

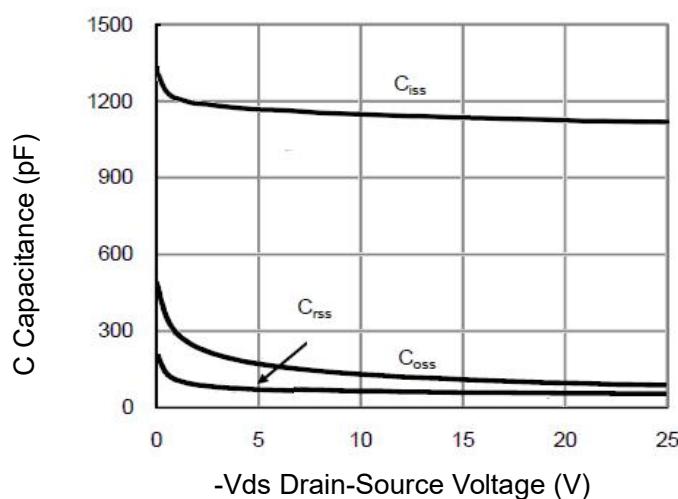


Figure 7 Capacitance vs Vds

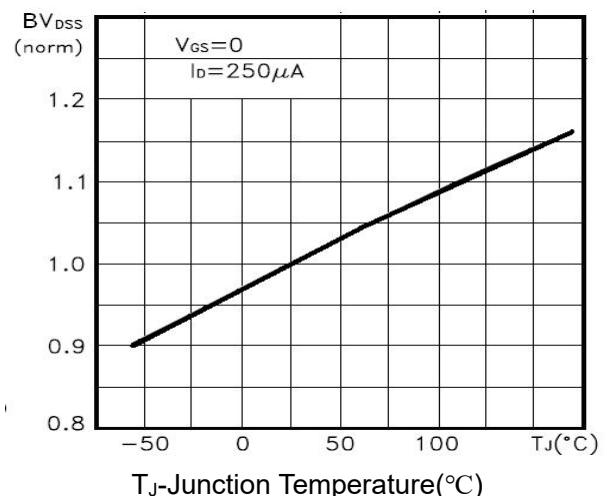


Figure 9 BV_{dss} vs Junction Temperature

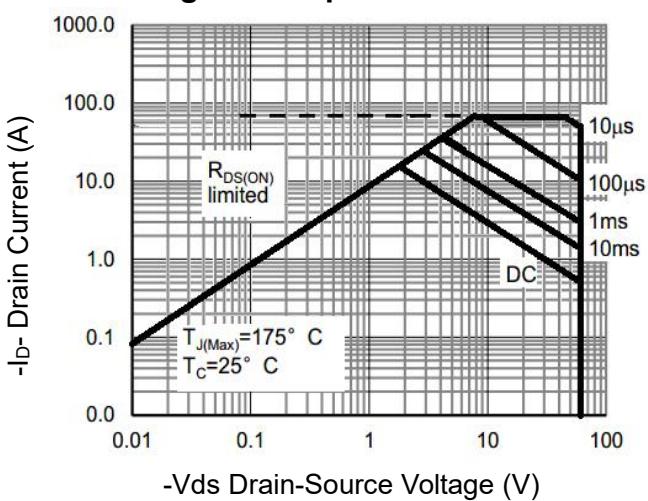


Figure 8 Safe Operation Area

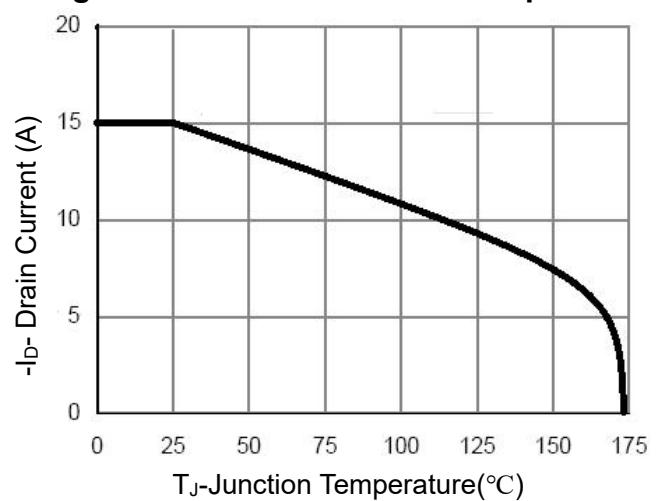


Figure 10 I_D Current De-rating

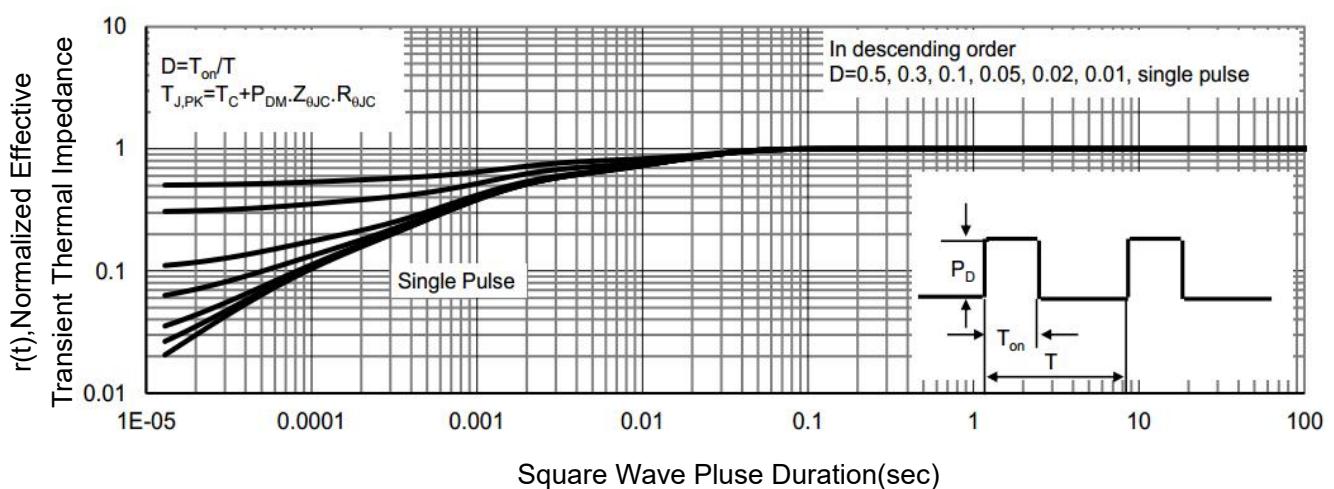
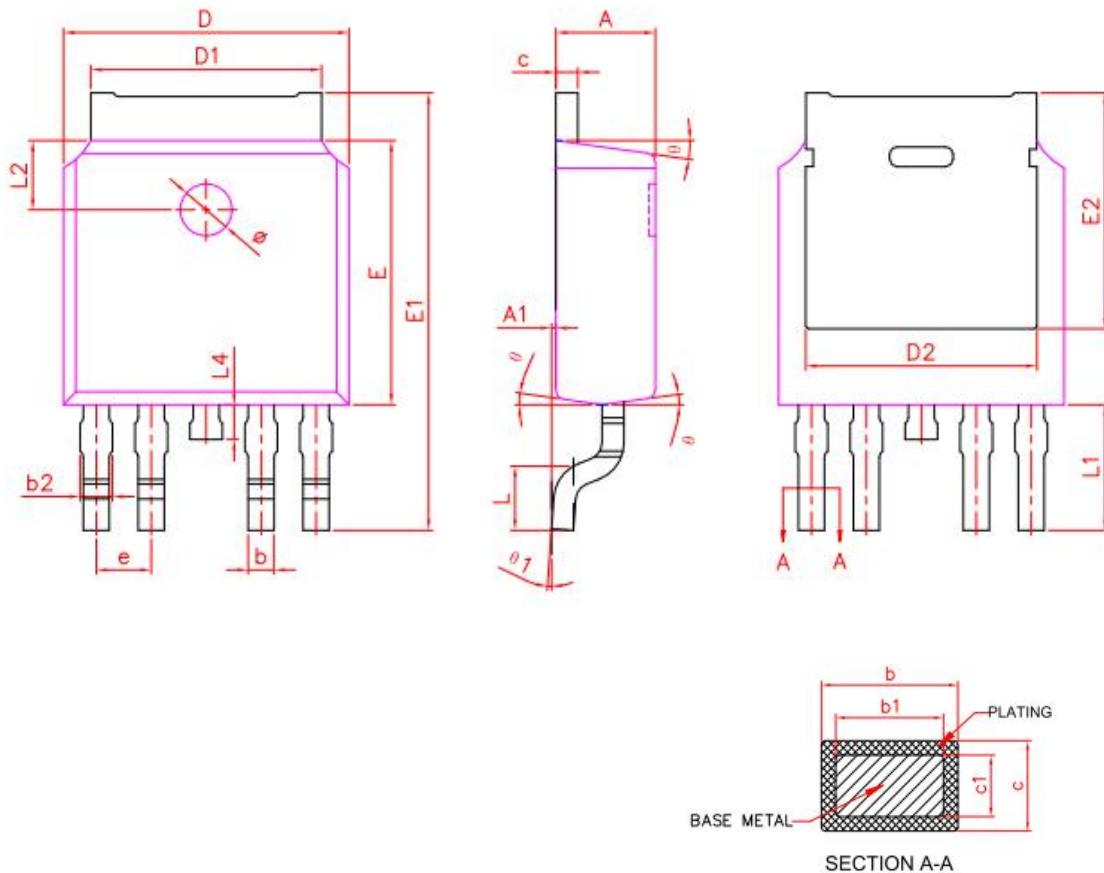


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252-4L Package Information



TO252-4L			
DIM.	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
A1	0.00	0.08	0.13
b	0.50	0.60	0.70
b1	0.57	0.60	0.63
b2	0.75REF		
c	0.46	0.508	0.58
c1	0.50	0.508	0.52
D	6.50	6.60	6.70
D1	5.10	5.334	5.46
D2	5.346REF		
E	6.00	6.10	6.20
E1	9.80	10.10	10.40
E2	5.446REF		
e	1.17	1.27	1.37
L	1.40	1.50	1.70
L1	2.90REF		
L2	1.60REF		
L4	0.60	0.80	1.00
Ø	Ø1.10	Ø1.20	Ø1.30
θ	5°	8°	10°
Ø1	0°	—	8°
All dimensions in millimeters			



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